

IN THE CLAIMS

Cancel claims 1-21 without prejudice or disclaimer, and add new claims 22-25 as follows:

22. (New) A method of manufacturing an electronic device, comprising the following steps:

providing a wiring substrate having a main surface and a rear surface opposed to the main surface;

a first step of placing a first electronic component on a first area of the main surface of the wiring substrate thereafter thermo-compression bonding the first electronic component by a thermo-compression bonding tool, bonding and fixing the first electronic component to the first area of the main surface of the wiring substrate, and electrically connecting first connecting portions provided in the first area of the main surface of the wiring substrate and electrode pads provided in the first electronic component by protruded electrodes interposed therebetween, respectively; and

a second step of supplying a soldering paste material to second connecting portions provided in a second area different from the first area of the main surface of the wiring

substrate, thereafter placing electrodes of a second electronic component on the second connecting portions with the soldering paste material interposed therebetween, respectively, and subsequently melting the soldering paste material to thereby electrically connect the second connecting portions of the wiring substrate and the electrodes of the second electronic component respectively,

wherein said first step is executed before the execution of said second step, and

wherein the supplying of the soldering paste material is carried out with a dispenser.

23. The method according to claim 22, wherein said first electronic component is an active part with circuits built therein, and wherein said second electronic component is a passive part.

24. The method according to claim 23, wherein said second electronic component has a height extending upward from the main surface of the wiring substrate which is higher than that of the first electronic component.

25. The method according to claim 24, wherein a temperature of the thermo-compression bonding tool at a time when the first electronic component is thermo-compression bonded, is higher than a melting point of the soldering paste material.